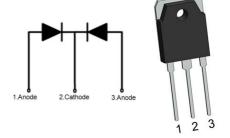


D40H60DPC

600V, 30A Ultra Fast Recovery Diode

Features

- High Voltage And High Speed Switching
- Low Forward Voltage Drop And Low Leakage Current
- TO-3P Package Offers Excellent Thermal Performance
- Pb-free Plating; RoHS Compliant



Application

- Power Factor Correction
- Free-Wheeling Diode

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit	
V_{RRM}	Peak repetitive reverse voltage	600	V	
I _{F(Av)} @Tc=100°C	Average Rectified Forward Current (Per device)	30	Α	
I _{FSM}	Non-repetitive Peak Surge Current		Α	
T _J , T _{STG}	Operating Junction and Storage Temperature -50~150		$^{\circ}$ C	

Thermal Resistance

Symbol	Parameter	Value	Unit
R _θ JC	Maximum Junction-to-Case thermal resistance	0.5	℃W
R _θ JA	Maximum Junction-to-Ambient thermal resistance	40	°CW

Electrical Characteristics (Per diode, TJ= 25°C, Unless Otherwise Specified)

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
V _F	Diode Forward Voltage	I _F =15A , T _C = 25°C	-	1.3	1.6	V
		I _F =15A , T _C = 100°C	-	-	1.5	V
I _R	Reverse Leakage Current	V _R =600V, T _C = 25°C	-	-	50	uA
		V _R =600V, T _C = 100°C	-	-	200	
T _{RR}	Maximum Reverse Recovery time	V _R =100V, I _F =15A	-	-	70	nS
I_{RR}	Maximum Reverse Recovery Current	di/dt=200A/us	-	-	8	Α
Q_RR	Maximum Reverse Recovery Charge	T _C = 25°C	-	-	280	nC
T _{RR}	Maximum Reverse Recovery time	V _R =100V, I _F =15A	-	-	100	nS
I_{RR}	Maximum Reverse Recovery Current	di/dt=200A/us	-	-	10	Α
Q_{RR}	Maximum Reverse Recovery Charge	T _C = 100°C	-	-	500	nC



Typical Performance Characteristics

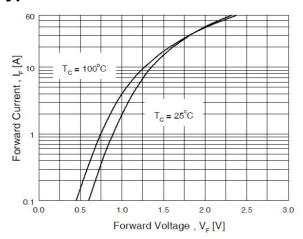


Figure 1. Typical Forward Voltage Drop vs. Forward Current

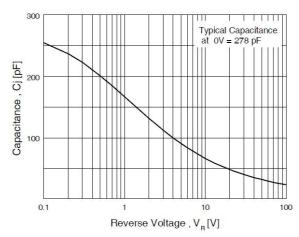


Figure 3. Typical Junction Capacitance

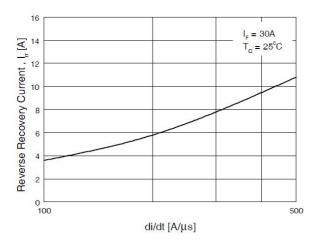


Figure 5. Typical Reverse Recovery Current vs. di/dt

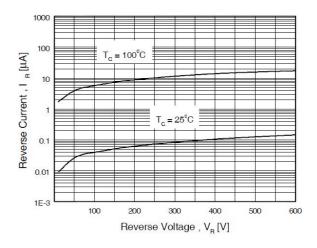


Figure 2. Typical Reverse Current vs. Reverse Voltage

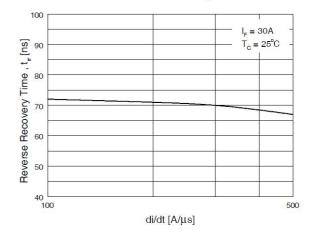


Figure 4. Typical Reverse Recovery Time vs. di/dt

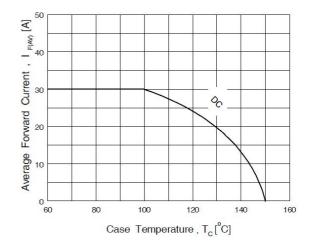
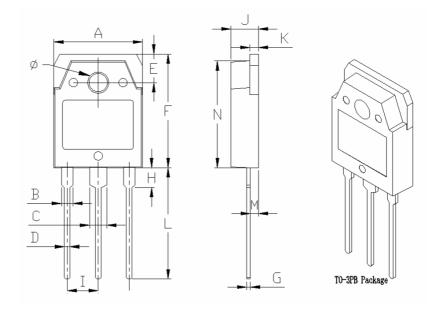


Figure 6. Forward Current Derating Curve



Mechanical Dimensions

Dim	Millimeters		
ווווט	MIN.	MAX.	
Α	15.50	15.70	
В	1.90	2.10	
С	2.90	3.10	
D	0.90	1.10	
Е	4.90	5.10	
F	19.80	20.00	
G	0.55	0.65	
Н	3.40	3.60	
I	5.45 BSC.		
J	4.70	4.9	
K	1.45	1.55	
L	19.9	20.10	
M	1.35	1.5	
N	18.6	18.8	
Ø	3.20	3.40	



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